

Fig.1

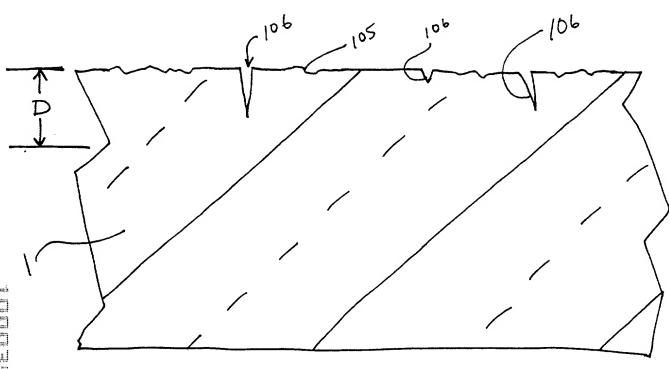
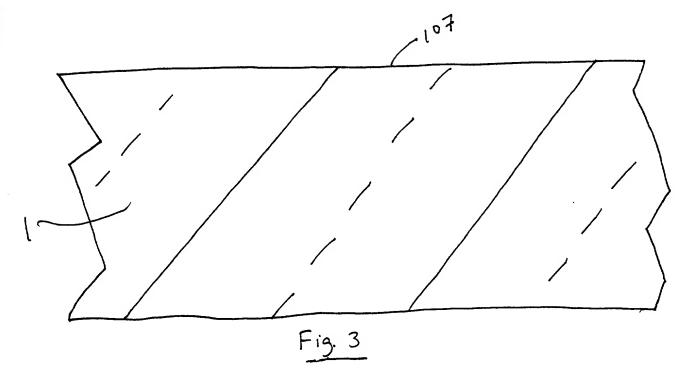
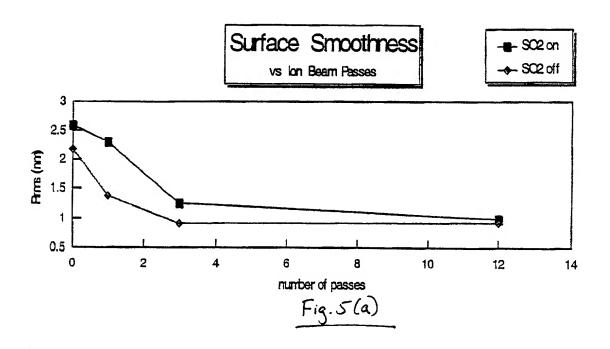


Fig. 2





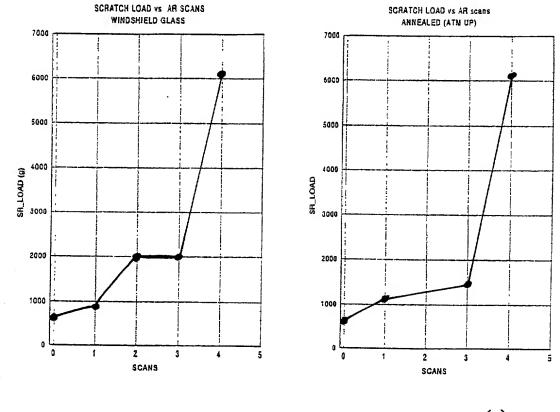
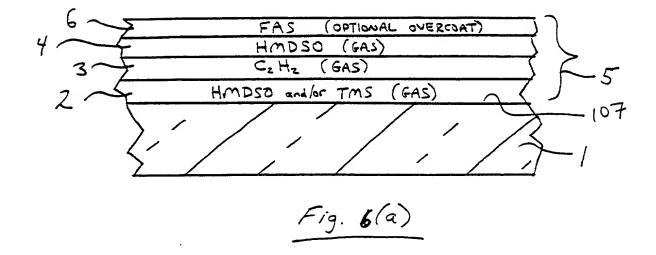
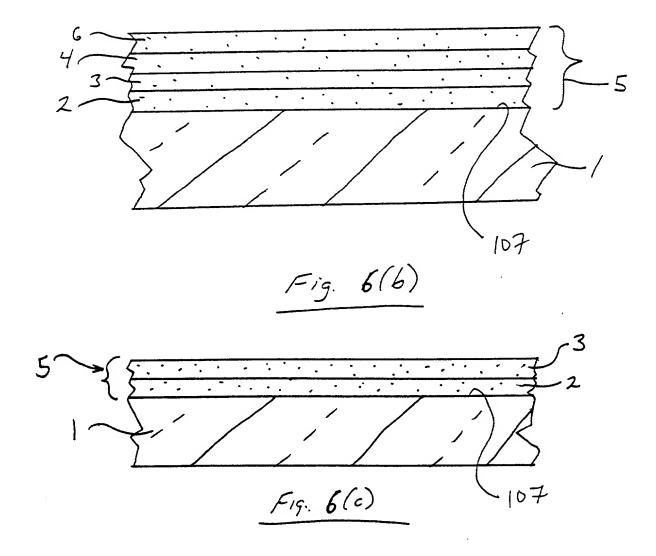


Fig. 5(6)

Fig. 5 (c)





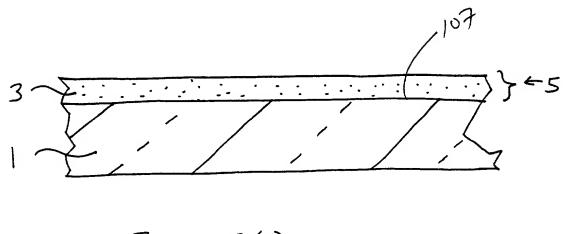
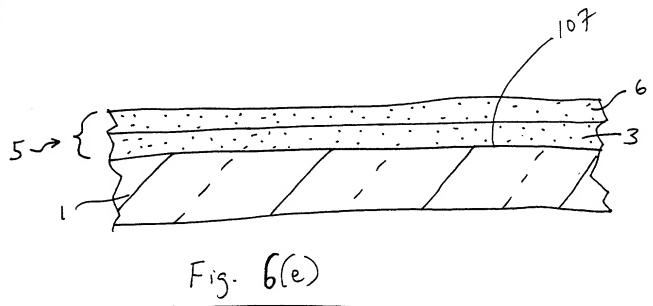
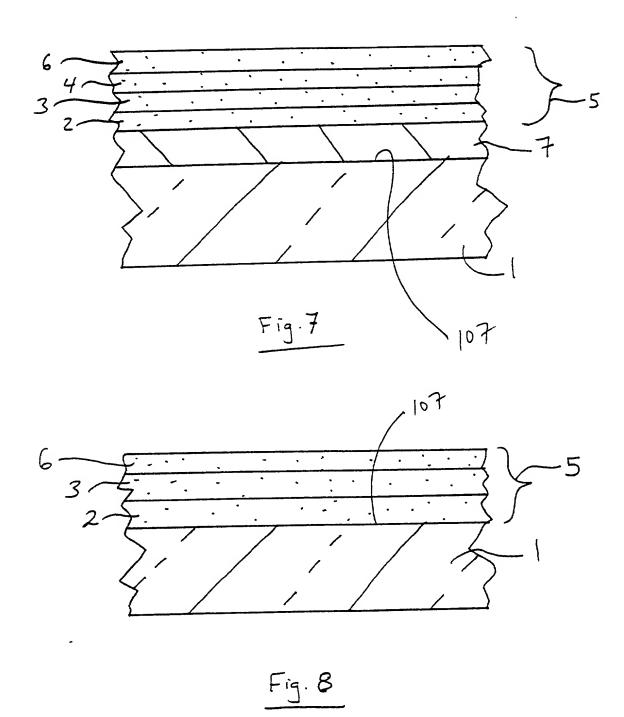
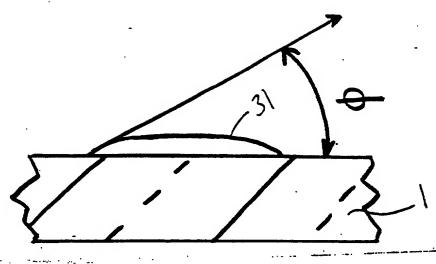
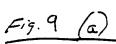


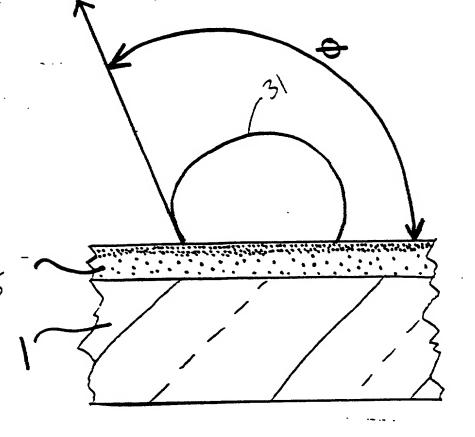
Fig. 6(d)



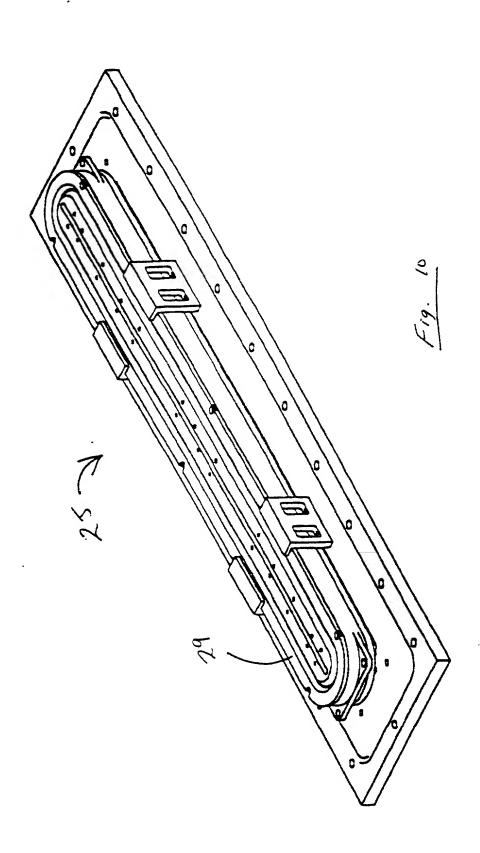




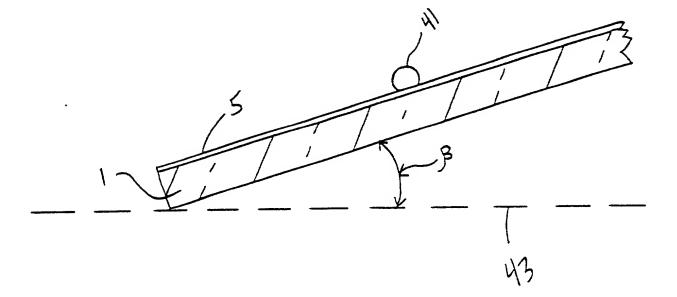




F19.9 (b)



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F19. 12

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$$\frac{CH_3}{CH_3} = \frac{CH_3}{CH_3} = \frac{CH_3}{CH_3} = \frac{CH_3}{CH_3} = \frac{CH_3}{CH_3}$$

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TMDSO Fig. 19

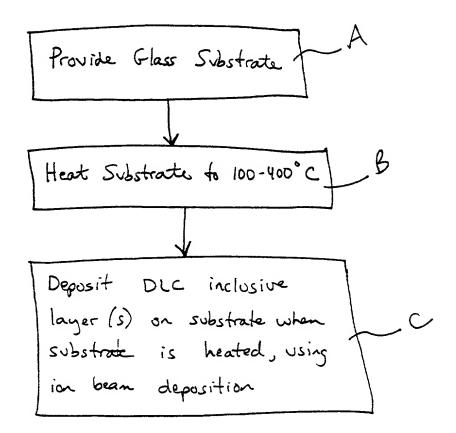
H

$$CH_3 - Si - O - Si - CH_3$$
 CH_3

$$\begin{array}{c|c}
OCH_{2}CH_{3} \\
\hline
OCH_{2}CH_{3}
\end{array}$$

$$\begin{array}{c|c}
OCH_{2}CH_{3}
\end{array}$$

$$\begin{array}{c|c}
OCH_{2}CH_{3}
\end{array}$$



· Fig. 21